

LM4570 Single-Ended Input Motor Driver

Check for Samples: [LM4570](#)

FEATURES

- Output Short Circuit Protection
- High Output Current Capability
- Wide Output Voltage Range
- Fast Turn on Time
- Output Short Circuit Protection
- Low Power Shutdown Mode
- Minimum external components

- Available in space-saving LLP package

APPLICATIONS

- Mobile Phones
- PDAs
- Video Game Systems

DESCRIPTION

The LM4570 is a single supply motor driver for improved sensory experience in mobile phones and other handheld devices. The LM4570 is capable of driving up to 192mA while operating from a 3V supply. Near rail-to-rail output swing under load ensures sufficient voltage drive for most DC motors, while the differential output drive allows the voltage polarity across the motor to be reversed quickly. Reversing the voltage gives the LM4570 the ability to drive a motor both clock-wise and counter clock-wise from a single supply.

The LM4570 features fast turn on time, and a wide input voltage range for precise speed control. A low power shutdown mode minimizes power consumption.

Thermal and output short circuit protection prevents the device from being damaged during fault conditions.

Table 1. Key Specifications

	VALUE	UNIT
■ High Output Current @ $V_{DD} = 3V$	192	mA
■ Fast Turn On Time @ 3V	2.4	ms
■ Quiescent Power Supply Current @ 3V	1.9	mA
■ Shutdown Current	0.1	μA (typ)



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Typical Application

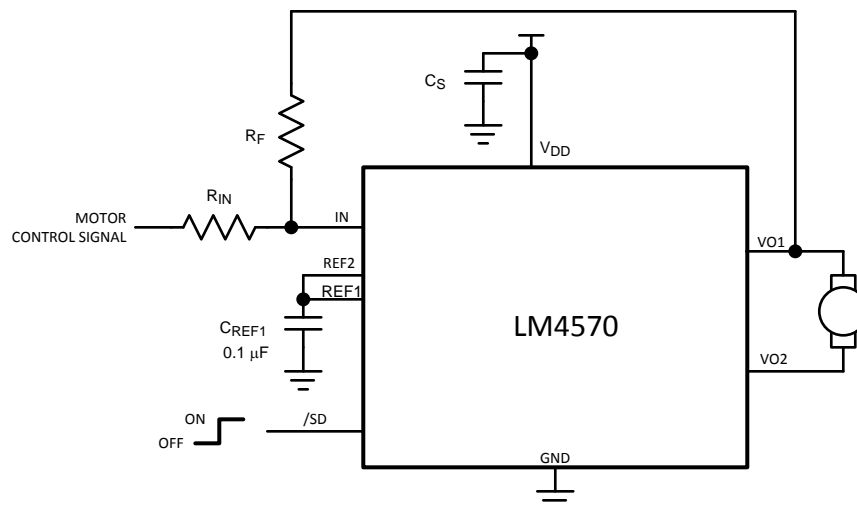


Figure 1. Typical Motor Driver Application Circuit

Connection Diagram

Leadless Leadframe Package (LLP) LQ Package

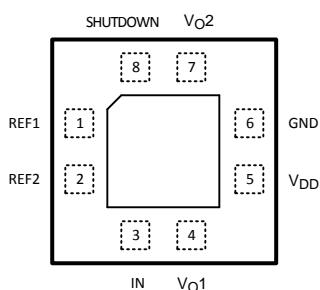


Figure 2. Top View
Order Number LM4570LQ
See NS Package Number LQB08A

LLP Marking

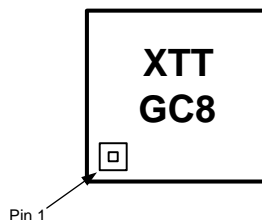


Figure 3. Top View
X - One digit date code
TT - Lot traceability
G - Boomer Family
C8 - LM4570LQ

Table 2. Ordering Information

Order Number	Package	Package DWG #	Transport Media	MSL Level	Green Status
LM4570LQ	8-Pin LLP	LQB08A	1000 units on tape and reel	1	RoHS & no Sb/Br
LM4570LQX	8-Pin LLP	LQB08A	4500 units on tape and reel	1	RoHS & no Sb/Br



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾

Supply Voltage ⁽²⁾	6.0V
Storage Temperature	–65°C to +150°C
Voltage at Any Input Pin	–0.3V ≥ to V _{DD} +0.3V
Power Dissipation ⁽³⁾	Internally Limited
ESD Susceptibility ⁽⁴⁾	2000V
ESD Susceptibility ⁽⁵⁾	200V
Junction Temperature (T _{JMAX})	150°C
Thermal Resistance	
θ _{JA} (LLP)	140°C/W

- (1) *Absolute Maximum Ratings* indicate limits beyond which damage to the device may occur. *Operating Ratings* indicate conditions for which the device is functional, but do not guarantee specific performance limits. *Electrical Characteristics* state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given; however, the typical value is a good indication of device performance.
- (2) All voltages are measured with respect to the ground pin, unless otherwise specified.
- (3) The maximum power dissipation must be de-rated at elevated temperatures and is dictated by T_{JMAX}, θ_{JC}, and the ambient temperature T_A. The maximum allowable power dissipation is P_{DMAX} = (T_{JMAX} – T_A) / θ_{JA} or the number given in the Absolute Maximum Ratings, whichever is lower. For the LM4570, T_{JMAX} = 150°C and the typical θ_{JA} for the LLP package is 140°C/W.
- (4) Human body model, 100pF discharged through a 1.5kΩ resistor.
- (5) Machine Model, 220pF–240pF discharged through all pins.

Operating Ratings

Temperature Range	
T _{MIN} ≤ T _A ≤ T _{MAX}	–40°C ≤ T _A ≤ 85°C
Supply Voltage	2.4V ≤ V _{DD} ≤ 5.5V

Electrical Characteristics $V_{DD} = 5V$

(1)(2)

The following specifications apply for $V_{DD} = 5V$, $A_{V-BTL} = 6dB$ unless otherwise specified. Limits apply for $T_A = 25^\circ C$.

Symbol	Parameter	Conditions	LM4570		Units (Limits)
			Typical	Limit	
			(3)		
⁽⁴⁾⁽⁵⁾ I_{DD}	Quiescent Power Supply Current	$V_{IN} = 0V$, $I_L = 0A$, No Load	2.5	5.5	mA (max)
		$V_{IN} = 0V$, $I_L = 0A$, $R_L = 30\Omega$	2.6	5.5	mA (max)
I_{SD}	Shutdown Current	$V_{SD} = GND$	0.1	1.5	μA (max)
V_{IH}	Logic Input High			1.4	V (min)
V_{IL}	Logic Input Low			0.4	V (max)
V_{OS}	Output Offset Voltage		5	± 35	mV (max)
I_{OUT}	Output Current	V_{OH} , $V_{OL} \leq 250mV$	268		mA
T_{WU}	Wake-up time		2.5		ms (max)
V_{OH}	Output High Voltage	$R_L = 30\Omega$ specified as $ V_{DD} - V_{OH} $	146	200	mV (max)
V_{OL}	Output Low Voltage	$R_L = 30\Omega$ specified as $ GND + V_{OH} $	106	200	mV (max)

(1) All voltages are measured with respect to the ground pin, unless otherwise specified.

(2) *Absolute Maximum Ratings* indicate limits beyond which damage to the device may occur. *Operating Ratings* indicate conditions for which the device is functional, but do not guarantee specific performance limits. *Electrical Characteristics* state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given; however, the typical value is a good indication of device performance.

(3) Typicals are measured at $25^\circ C$ and represent the parametric norm.

(4) Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

(5) Datasheet min/max specification limits are guaranteed by design, test, or statistical analysis.

Electrical Characteristics $V_{DD} = 3V$

(1)(2)

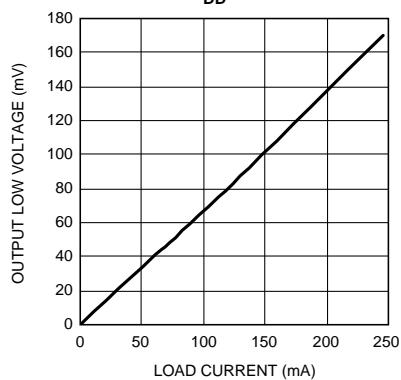
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Symbol	Parameter	Conditions	LM4570		Units (Limits)
			Typical	Limit	
			(3)		
⁽⁴⁾⁽⁵⁾ I_{DD}	Quiescent Power Supply Current	$V_{IN} = 0V$, $I_L = 0A$, No Load	1.9	4	mA (max)
		$V_{IN} = 0V$, $I_L = 0A$, $R_L = 30\Omega$	1.95	4	
I_{SD}	Shutdown Current	$V_{SD} = GND$	0.1	1.0	μA (max)
V_{IH}	Logic Input High			1.4	V (min)
V_{IL}	Logic Input Low			0.4	V (max)
V_{OS}	Output Offset Voltage		5	± 35	mV (max)
I_{OUT}	Output Current	V_{OH} , $V_{OL} \leq 200mV$	192		mA
T_{WU}	Wake-up time		2.4		ms (max)
V_{OH}	Output High Voltage	$R_L = 30\Omega$ specified as $ V_{DD} - V_{OH} $	90	110	mV (max)
V_{OL}	Output Low Voltage	$R_L = 30\Omega$ specified as $ V_{DD} - V_{OH} $	63	110	mV (max)

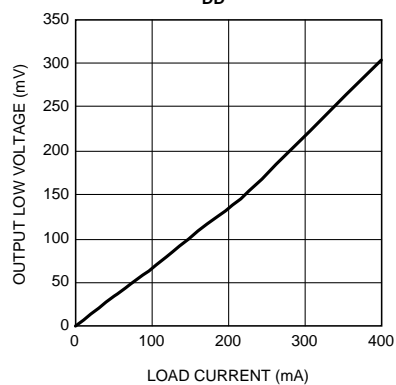
- (1) All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) *Absolute Maximum Ratings* indicate limits beyond which damage to the device may occur. *Operating Ratings* indicate conditions for which the device is functional, but do not guarantee specific performance limits. *Electrical Characteristics* state DC and AC electrical specifications under particular test conditions which guarantee specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not guaranteed for parameters where no limit is given; however, the typical value is a good indication of device performance.
- (3) Typicals are measured at $25^\circ C$ and represent the parametric norm.
- (4) Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).
- (5) Datasheet min/max specification limits are guaranteed by design, test, or statistical analysis.

Typical Performance Characteristics

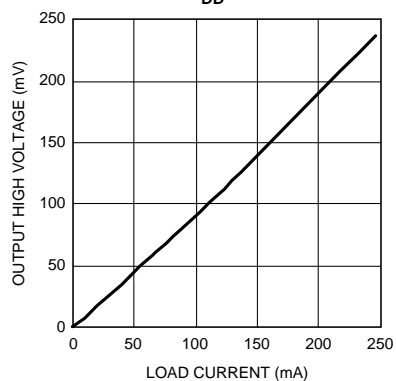
**Output Low Voltage
vs
Load Current
 $V_{DD} = 3V$**



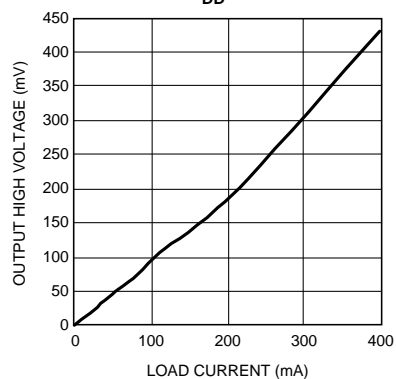
**Output Low Voltage
vs
Load Current
 $V_{DD} = 5V$**



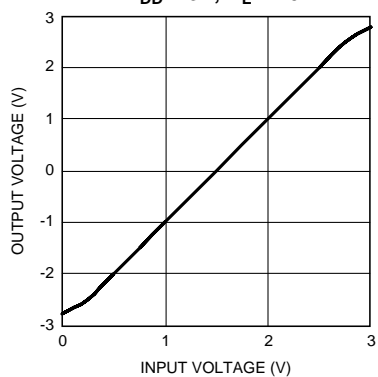
**Output High Voltage
vs
Load Current
 $V_{DD} = 3V$**



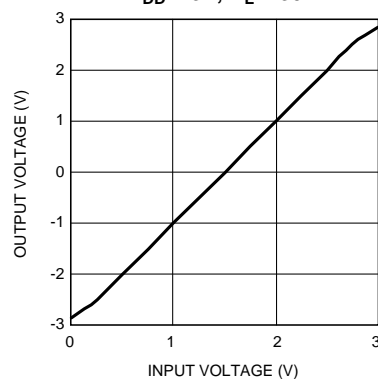
**Output High Voltage
vs
Load Current
 $V_{DD} = 5V$**



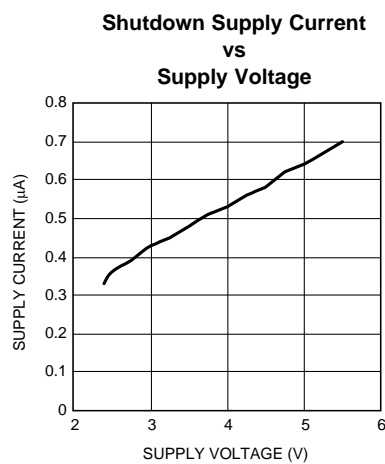
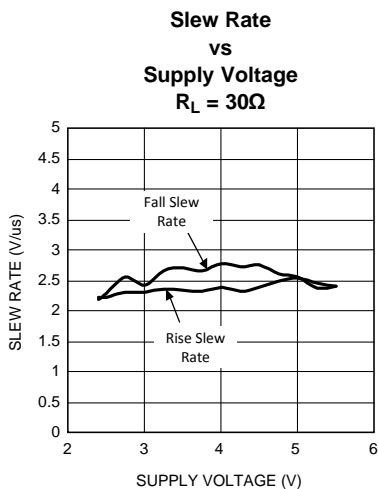
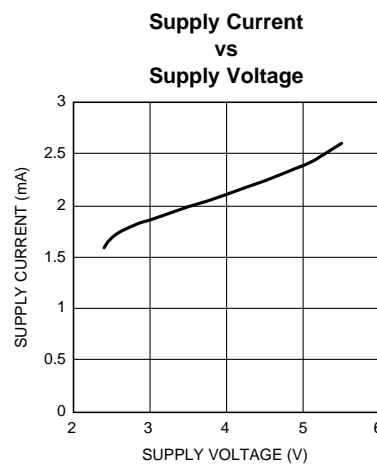
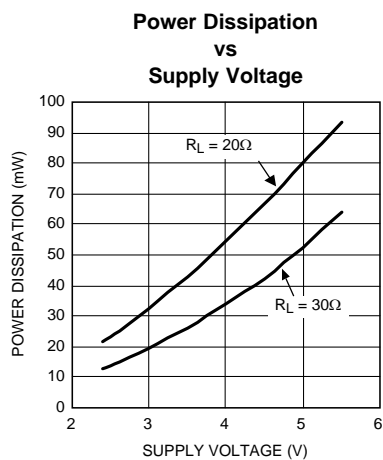
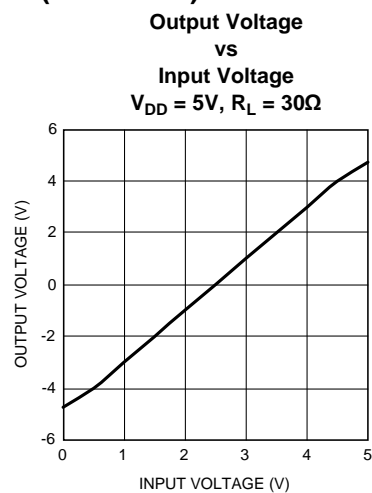
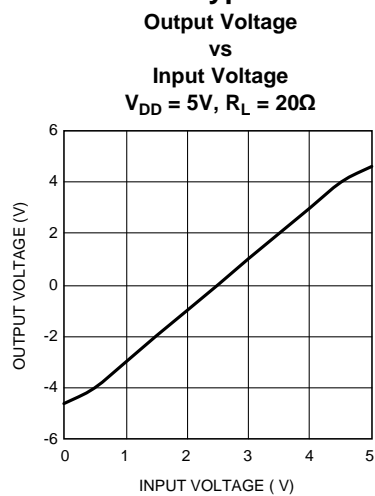
**Output Voltage
vs
Input Voltage
 $V_{DD} = 3V, R_L = 20\Omega$**



**Output Voltage
vs
Input Voltage
 $V_{DD} = 3V, R_L = 30\Omega$**

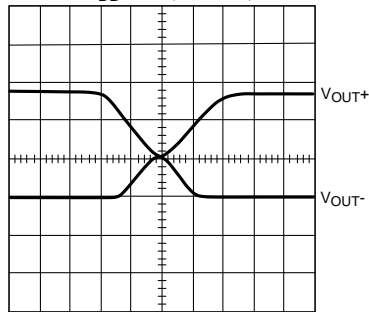


Typical Performance Characteristics (continued)

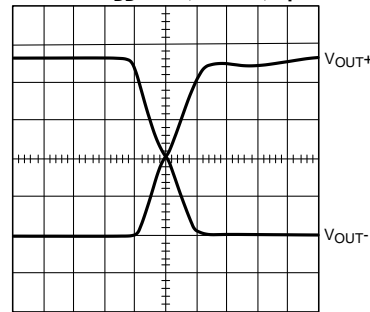


Typical Performance Characteristics (continued)

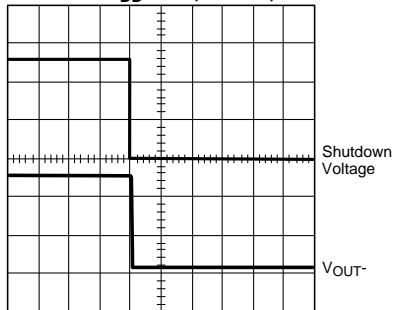
Output Transition High to Low, Low to High

 $V_{DD} = 3V$, 1V/div, 400ns/div

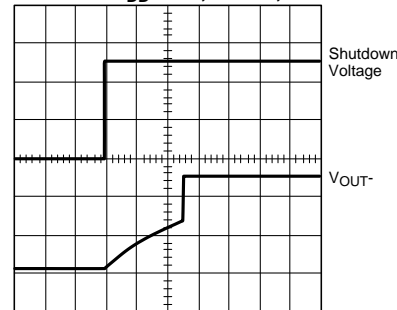
Output Transition High to Low, Low to High

 $V_{DD} = 5V$, 1V/div, 1μs/div

Turn-Off Time

 $V_{DD} = 5V$, 2V/div, 1ms/div

Turn-On Time

 $V_{DD} = 5V$, 2V/div, 1ms/div

Application Information

BRIDGE CONFIGURATION EXPLANATION

The LM4570 uses a bridged architecture that drives a load differentially. The BTL design offers several advantages over a single-ended design. The device outputs, V_{O1} and V_{O2} , both source and sink current, which means that the polarity of the voltage across the motor can be reversed quickly (Figure 2). A single-ended device would need to operate from split supplies to achieve this behavior. The ability to reverse the voltage polarity is necessary in applications where a negative (reverse polarity) pulse is used to quickly stop the motor. If the drive voltage is just removed from the motor (not reversed) then the motor will continue to spin until the residual energy stored in the windings has dissipated.

The output voltage of the LM4570 is determined by the difference between the input voltage and V_{REF1} , as well as the differential gain of the device. The output voltage is given by the following:

$$V_{O1} - V_{O2} = A_{VD}(V_{IN} - V_{REF1}) \quad (1)$$

For input voltages that are less than the reference voltage, the differential output voltage is negative. For input voltages that are greater than the reference voltage, the differential output voltage is positive. For example, when operating from a 5V supply ($V_{REF1} = 2.5V$) and with a differential gain of 6dB, with a 1V input, the voltage measured across V_{O1} and V_{O2} is -3V, with a 4V input, the differential output voltage is +3V.

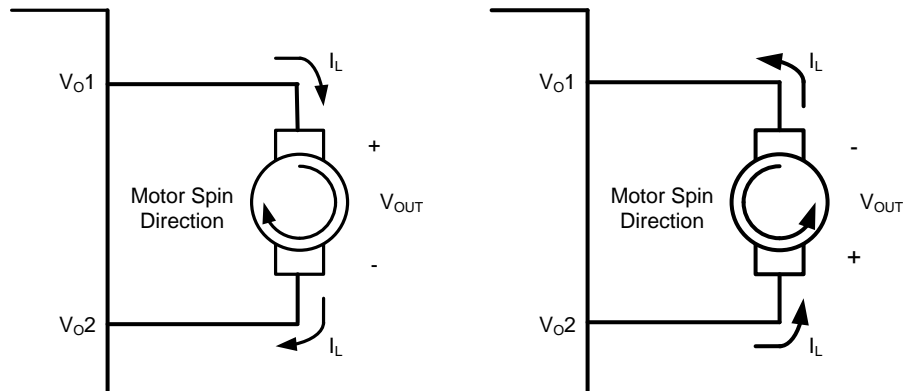


Figure 4. Voltage Polarity and Motor Direction

GAIN SETTING

The resistors R_{IN} and R_F set the gain of the LM4570, given by:

$$V_{VD} = 2 \times (R_F / R_{IN}) \quad (2)$$

Where A_{VD} is the differential gain. A_{VD} differs from single-ended gain by a factor of 2. This doubling is due to the differential output architecture of the LM4570. Driving the load differentially doubles the output voltage compared to a single-ended output amplifier under the same conditions.

POWER DISSIPATION

The Power Dissipation vs. Supply Voltage graph in the Operating Curves section shows the power dissipation of the LM4570 with the input equal to the supply voltage, meaning the outputs swing rail-to-rail. This configuration results in the output devices of the LM4570 operating in the linear region, essentially very small resistors determined by the $R_{DS(ON)}$ of the output devices. Under these conditions, the power dissipation is dominated by the $I \cdot R$ drop associated with the output current across the $R_{DS(ON)}$ of the output transistors, thus the power dissipation is very low (60mW for a 800mW output).

When the input voltage is not equal to GND or V_{DD} , the power dissipation of the LM4570 increases (Figure 3). Under these conditions, the output devices operate in the saturation region, where the devices consume current in addition to the current being steered to the load, increasing the power dissipation. Power dissipation for typical motor driving applications should not be an issue since the most of the time the device outputs will be driven rail-to-rail.

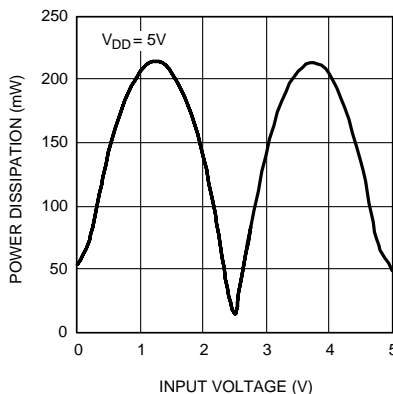


Figure 5. Power Dissipation vs. Input Voltage

EXPOSED-DAP MOUNTING CONSIDERATIONS

The LM4570 is available in an 8-pin LLP package which features an exposed DAP (die attach paddle). The exposed DAP provides a direct thermal conduction path between the die and the PCB, improving the thermal performance by reducing the thermal resistance of the package. Connect the exposed DAP to GND through a large pad beneath the device, and multiple vias to a large unbroken GND plane. For best thermal performance, connect the DAP pad to a GND plane on an outside layer of the PCB. Connecting the DAP to a plane on an inner layer will result in a higher thermal resistance. Ensure efficient thermal conductivity by plugging and tenting the vias with plating and solder mask, respectively.

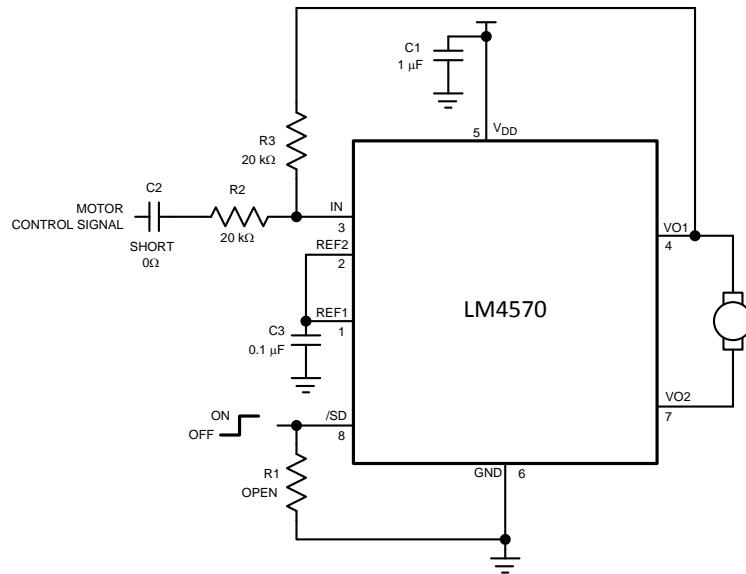
POWER SUPPLY BYPASSING

Good power supply bypassing is critical for proper operation. Locate both the REF1 and V_{DD} bypass capacitors as close to the device as possible. Typical applications employ a regulator with a 10 μ F tantalum or electrolytic capacitor and a ceramic bypass capacitor which aid in supply stability. This does not eliminate the need for bypass capacitors near the LM4570. Place a 1 μ F ceramic capacitor as close to V_{DD} as possible. Place a 0.1 μ F capacitor as close to REF1 as possible. Smaller values of C_{REF1} may be chosen for decreased turn on times.

SHUTDOWN FUNCTION

The LM4570 features a low power shutdown mode that disables the device and reduces quiescent current consumption to 0.1 μ A. Driving /SD Low disables the amplifiers and bias circuitry, and drives V_{REF1} and the outputs to GND. Connect /SD to V_{DD} for normal operation.

DEMO BOARD LAYOUT



Revision History

Rev	Date	Description
1.0	04/13/06	Initial release.
1.01	07/28/09	Added the Ordering Information table.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Samples (Requires Login)
LM4570LQ/NOPB	ACTIVE	WQFN	NGP	8	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	
LM4570LQX/NOPB	ACTIVE	WQFN	NGP	8	4500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

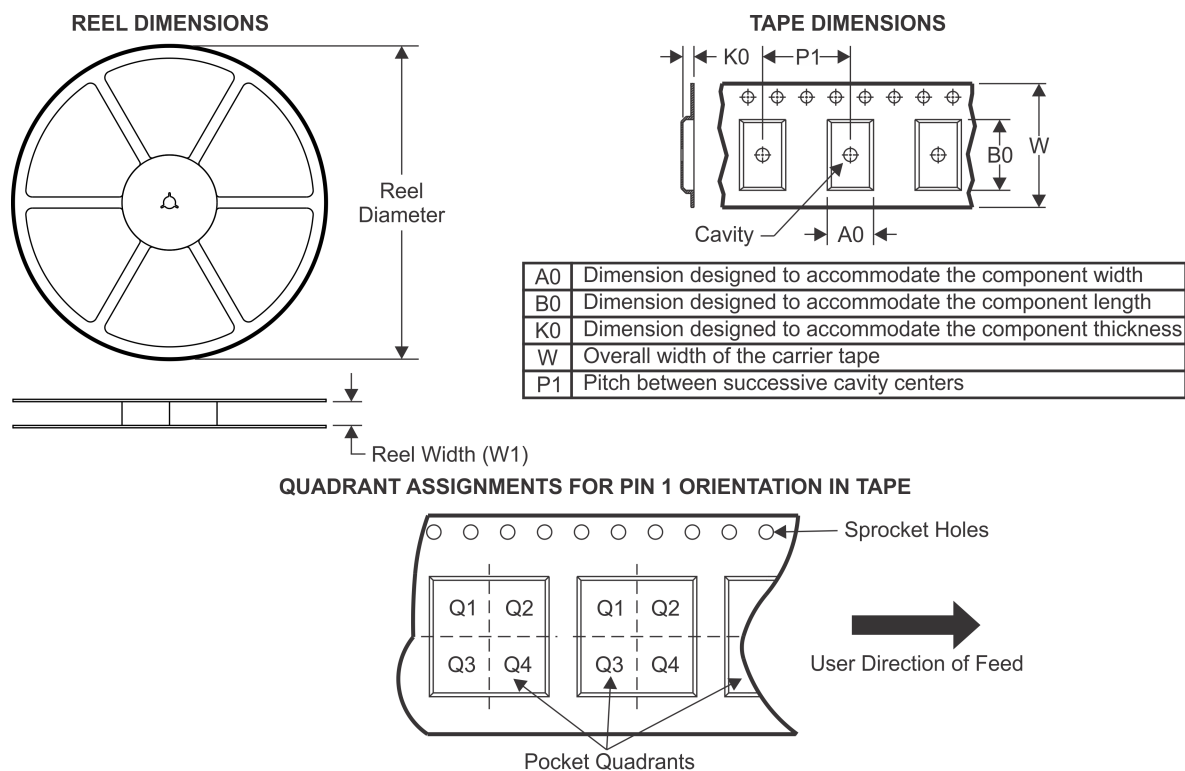
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM4570LQ/NOPB	WQFN	NGP	8	1000	178.0	12.4	2.2	2.2	1.0	8.0	12.0	Q1
LM4570LQX/NOPB	WQFN	NGP	8	4500	330.0	12.4	2.2	2.2	1.0	8.0	12.0	Q1

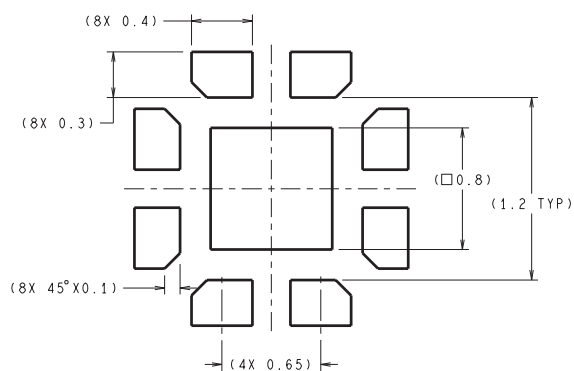
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

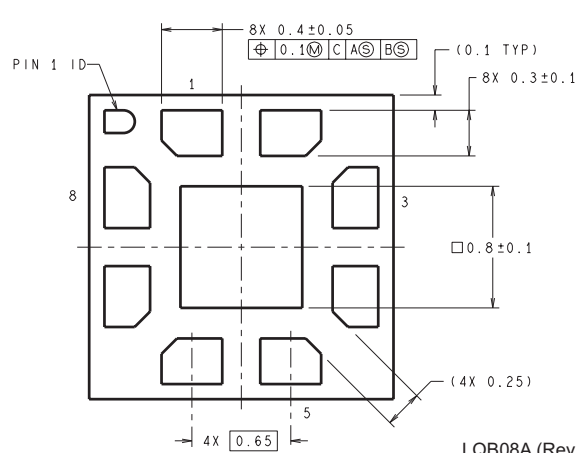
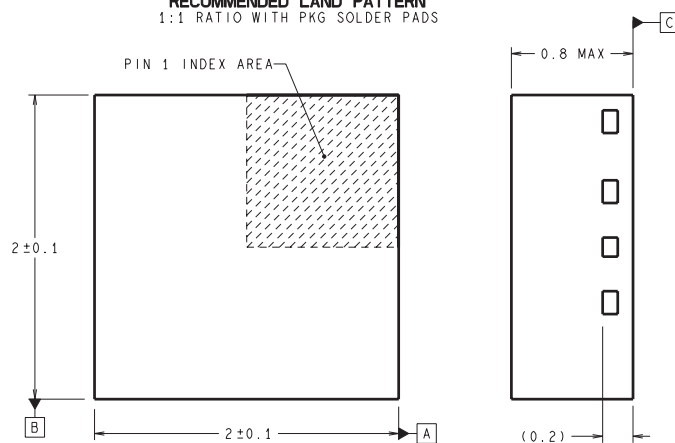
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM4570LQ/NOPB	WQFN	NGP	8	1000	203.0	190.0	41.0
LM4570LQX/NOPB	WQFN	NGP	8	4500	358.0	343.0	63.0

NGP0008A



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PKG SOLDER PADS



LQB08A (Rev B)

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